



Material Content Data Sheet



Sales Product Name	BSC070N10NS5SC	Issued	16. May 2021
MA#	MA005349262		
Package	PG-WSON-8-2	Weight*	96.89 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.216	1.25	1.25	12545	12545
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		118	
	non noble metal	zinc	7440-66-6	0.046	0.05		470	
	non noble metal	iron	7439-89-6	0.912	0.94		9410	
	non noble metal	copper	7440-50-8	37.021	38.20	39.20	382077	392075
wire	noble metal	gold	7440-57-5	0.063	0.06	0.06	650	650
encapsulation	organic material	carbon black	1333-86-4	0.040	0.04		409	
	plastics	epoxy resin	-	1.823	1.88		18813	
	inorganic material	silicondioxide	60676-86-0	17.951	18.53	20.45	185265	204487
leadfinish	non noble metal	tin	7440-31-5	1.365	1.41	1.41	14087	14087
plating	noble metal	silver	7440-22-4	0.839	0.87	0.87	8654	8654
solder	noble metal	silver	7440-22-4	0.034	0.04		353	
	non noble metal	tin	7440-31-5	0.068	0.07		707	
	non noble metal	lead	7439-92-1	1.267	1.31	1.42	13077	14137
heat sink clip	inorganic material	phosphorus	7723-14-0	0.010	0.01		106	
	non noble metal	zinc	7440-66-6	0.041	0.04		424	
	non noble metal	iron	7439-89-6	0.822	0.85		8481	
	non noble metal	copper	7440-50-8	33.366	34.44	35.34	344354	353365
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com